

FORM PTO-1449
(Modified)U.S. Department of Commerce
Patent and Trademark Office

Attorney Docket No.: COOL-01500

Serial No.: 10/643,638

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Applicants: Peng Zhou et al

(37 CFR § 1.98(b))

Filing Date: August 18, 2003

Group Art Unit: 3753

U.S. PATENT DOCUMENTS

Examiner Initials		Serial / Patent Number	Issue Date	Applicant / Patentee	Class	Subclass	Filing Date
FZ	AA	5,179,500	01/12/93	Koubek et al.	361	385	04/02/91
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Examiner:

Philip Rec

Date Considered:

1/26/2005

EXAMINER:

Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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F2	AA	6,632,719 B1	10/14/03	DeBoer et al.	438	381	08/31/00
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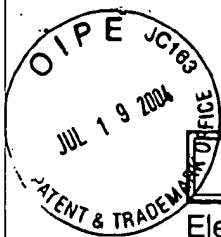
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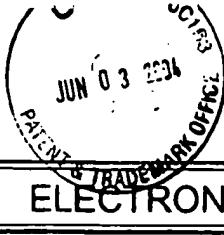
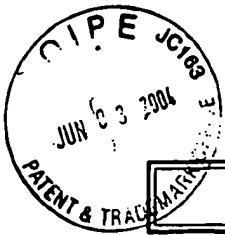


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











































Title of Invention	BOILING TEMPERATURE DESIGN IN PUMPED MICROCHANNEL COOLING LOOPS						
Application Number: 10/643638							
Confirmation Number: 4432							
First Named Applicant: Peng Zhou							
Attorney Docket Number:							
Search string: (3948316 or 5161089 or 5228502 or 5239443 or 5265670 or 5978220 or 5993750 or 6729383).pn.							
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
PZ	1	3948316	1976-04-06	Souriau			
	2	5161089	1992-11-03	Chu et al.			
	3	5228502	1993-07-20	Chu et al.			
	4	5239443	1993-08-24	Fahey et al.			
	5	5265670	1993-11-30	Zingher			
	6	5978220	1999-11-02	Frey et al.			
	7	5993750	1999-11-30	Ghosh et al.			
FZ	8	6729383	2004-05-04	Cannell et al.	B1		
Signature							
Examiner Name				Date			
Philip Zec				1/26/2005			



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	19	6431260	2002-08-13	Agonafer et al.	B1
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	24	6601643	2003-08-05	Cho et al.	B2
✓	25	6609560	2003-08-26	Cho et al.	B2
PZ	26	6651735	2003-11-25	Cho et al.	B2

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Note: Applicant is not required to submit a paper copy of cited US Published Applications

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Signature

Examiner Name	Date
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↓	AZ	J. C. Y. Koh et al., "Heat Transfer of Microstructure for Integrated Circuits", 1986, Int. Comm. Heat Mass Transfer, Vol. 13, pages 89-98.						
F2	BA	Snezana Konecni et al., "Convection Cooling of Microelectronic Chips", 1992, InterSociety Conference on Thermal Phenomena, pages 138-144.						

Examiner:

Philip Zec

Date Considered:

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OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)					
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Examiner: Philip Lee				Date Considered: 1/26/2005			
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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary)				Applicants: Peng Zhou et al.	
				Filing Date: August 18, 2003	Group Art Unit: 3753
(37 CFR § 1.98(b))					
OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)					
F2	GL	Gokturk Tune et al., <u>Heat transfer in rectangular microchannels</u> , 2002, Int. J. Heat Mass Transfer, 45 (2002), pages 765-773.			
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Examiner:		Philip Zee			
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